



## Features

- ▶ Standard JEDEC package outlines
- ▶ Multi-die production capability
- ▶ Turnkey test services, including strip test options
- ▶ Green materials are standard – Pb-free and RoHS compliant

# PDIP

PDIP (Plastic Dual In-line Package) has a proven track record and is a common choice for assembly of logic, memory, microcontrollers and other devices for use in a wide range of applications.

## Process Highlights

- ▶ Wafer backgrinding services available
- ▶ Multiple die and die stacking capability
- ▶ PPF lead finish is standard, Matte Sn is optional
- ▶ Laser mark on package body
- ▶ Au plated PCC wire is standard, Au and Ag wire available

## Reliability Qualification

Amkor package qualification uses three independent production lots and a minimum of 77 units per test group. All testing includes JSTD-020 moisture preconditioning.

- ▶ uHAST: 130°C/85% RH, No bias, 96 hours
- ▶ Temperature Cycle: -65°C/+150°C, 500 cycles
- ▶ High Temperature Storage: 150°C, 1000 hours

## Services and Support

Amkor has a broad base of resources available to help customers bring quality products to market quickly and at the lowest possible cost.

- ▶ Full package characterization
- ▶ Thermal, mechanical stress and electrical performance modeling
- ▶ Turnkey assembly, test and drop ship
- ▶ World class reliability testing and failure analysis

# PDIP

## Test Services

- ▶ Program generation/conversion
- ▶ Wafer probe
- ▶ Burn-in capabilities
- ▶ -55°C to +165°C test available
- ▶ Strip test available

## Shipping

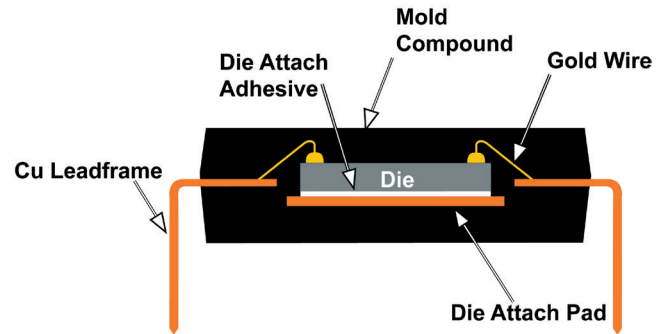
- ▶ Clear anti-static tube, 20 inch
- ▶ Drop ship

## Configuration Options

### PDIP Nominal Package Dimensions (mils)

Lead Count	Shoulder Width	Body Width	Body Length	Body Thickness	Standoff	Lead Pitch	JEDEC
8	300	252	365	130	15	100	MS-001
14	300	252	750	130	15	100	MS-001
16	300	252	750	130	15	100	MS-001

## Cross Section PDIP



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